TITLE

PRODUCT AND METHOD FOR PLACING PARTICLES ON CONTACT PADS OF ELECTRONIC DEVICES

ABSTRACT OF THE DISCLOSURE

An article for use in placing particles on contact pads of electronic devices comprises a surface having an array of tacky and non-tacky areas thereon, wherein the tacky areas are disposed either co-planar with the non-tacky areas or below the plane of the non-tacky areas, the tacky areas having a size and bonding strength suitable for adhesion of one particle thereto and is used to place particles from the tacky areas to contact pads of electronic devices, such as circuit boards used in semiconductor applications.

Figures 1 and 2

This Sheet Has Been Replaced

